

ADC124S021 4 Channel, 50 ksps to 200 ksps, 12-Bit A/D Converter

Check for Samples: ADC124S021

FEATURES

- Specified over a range of sample rates.
- · Four input channels
- Variable power management
- Single power supply with 2.7V 5.25V range

APPLICATIONS

- Portable Systems
- · Remote Data Acquisition
- Instrumentation and Control Systems

DESCRIPTION

The ADC124S021 is a low-power, four-channel CMOS 12-bit analog-to-digital converter with a high-speed serial interface. Unlike the conventional practice of specifying performance at a single sample rate only, the ADC124S021 is fully specified over a sample rate range of 50 ksps to 200 ksps. The converter is based on a successive-approximation register architecture with an internal track-and-hold circuit. It can be configured to accept up to four input signals at inputs IN1 through IN4.

The output serial data is straight binary, and is compatible with several standards, such as SPI™, QSPI™, MICROWIRE, and many common DSP serial interfaces.

The ADC124S021 operates with a single supply that can range from +2.7V to +5.25V. Normal power consumption using a +3V or +5V supply is 2.2 mW and 7.9 mW, respectively. The power-down feature reduces the power consumption to just 0.14 μ W using a +3V supply, or 0.32 μ W using a +5V supply.

The ADC124S021 is packaged in a 10-lead MSOP package. Operation over the industrial temperature range of -40°C to +85°C is guaranteed.



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

Table 1. Key Specifications

		VALUE	UNIT
DNL		+0.4 / -0.2	LSB (typ)
INL		± 0.35	LSB (typ)
SNR		72.0	dB (typ)
Power Consumption		2.2	mW (typ)
	5V Supply	7.9	mW (typ)

Table 2. Pin-Compatible Alternatives by Resolution and Speed⁽¹⁾

Resolution	Specified for Sample Rate Range of:				
	50 to 200 ksps	200 to 500 ksps	500 ksps to 1 Msps		
12-bit	ADC124S021	ADC124S051	ADC124S101		
10-bit	ADC104S021	ADC104S051	ADC104S101		
8-bit	ADC084S021	ADC084S051	ADC084S101		

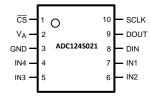
(1) All devices are fully pin and function compatible.



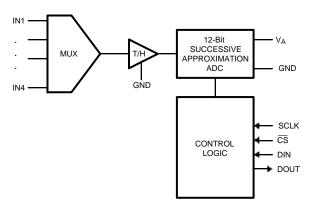
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Connection Diagram



Block Diagram



Pin Descriptions and Equivalent Circuits

Pin No.	Symbol	Description
ANALOG I/O		
4-7	IN1 to IN4	Analog inputs. These signals can range from 0V to V _A .
DIGITAL I/O	•	
10	SCLK	Digital clock input. This clock directly controls the conversion and readout processes.
9	DOUT	Digital data output. The output samples are clocked out of this pin on falling edges of the SCLK pin.
8	DIN	Digital data input. The ADC124S021's Control Register is loaded through this pin on rising edges of the SCLK pin.
1	CS	Chip select. On the falling edge of $\overline{\text{CS}}$, a conversion process begins. Conversions continue as long as $\overline{\text{CS}}$ is held low.
POWER SUPPLY		
2	V _A	Positive supply pin. This pin should be connected to a quiet $+2.7V$ to $+5.25V$ source and bypassed to GND with a 1 μ F capacitor and a 0.1 μ F monolithic capacitor located within 1 cm of the power pin.
3	GND	The ground return for the supply and signals.



Absolute Maximum Ratings (1) (2)

Supply Voltage V _A	-0.3V to 6.5V
Voltage on Any Pin to GND	-0.3V to V _A +0.3V
Input Current at Any Pin (3)	±10 mA
Package Input Current ⁽³⁾	±20 mA
Power Consumption at T _A = 25°C	See (4)
ESD Susceptibility ⁽⁵⁾ Human Body Model Machine Model	2500V 250V
Junction Temperature	+150°C
Storage Temperature	−65°C to +150°C

- (1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is functional, but do not guarantee specific performance limits. For guaranteed specifications and test conditions, see the Electrical Characteristics. The guaranteed specifications apply only for the test conditions listed. Some performance characteristics may degrade when the device is not operated under the listed test conditions.
- 2) All voltages are measured with respect to GND = 0V, unless otherwise specified.
- (3) When the input voltage at any pin exceeds the power supply (that is, V_{IN} < GND or V_{IN} > V_A), the current at that pin should be limited to 10 mA. The 20 mA maximum package input current rating limits the number of pins that can safely exceed the power supplies with an input current of 10 mA to two. The Absolute Maximum Rating specification does not apply to the V_A pin. The current into the V_A pin is limited by the Analog Supply Voltage specification.
- (4) The absolute maximum junction temperature (T_Jmax) for this device is 150°C. The maximum allowable power dissipation is dictated by T_Jmax, the junction-to-ambient thermal resistance (θ_{JA}), and the ambient temperature (T_A), and can be calculated using the formula P_DMAX = (T_Jmax T_A)/θ_{JA}. The values for maximum power dissipation listed above will be reached only when the device is operated in a severe fault condition (e.g. when input or output pins are driven beyond the power supply voltages, or the power supply polarity is reversed). Obviously, such conditions should always be avoided.
- (5) Human body model is 100 pF capacitor discharged through a 1.5 kΩ resistor. Machine model is 220 pF discharged through zero ohms.

Operating Ratings (1) (2)

Operating Temperature Range	-40°C ≤ T _A ≤ +85°C
V _A Supply Voltage	+2.7V to +5.25V
Digital Input Pins Voltage Range	-0.3V to V _A
Clock Frequency	50 kHz to 16 MHz
Analog Input Voltage	0V to V _A

- (1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is functional, but do not guarantee specific performance limits. For guaranteed specifications and test conditions, see the Electrical Characteristics. The guaranteed specifications apply only for the test conditions listed. Some performance characteristics may degrade when the device is not operated under the listed test conditions.
- (2) All voltages are measured with respect to GND = 0V, unless otherwise specified.

Package Thermal Resistance

Package	θ_{JA}
10-lead MSOP	190°C / W

Product Folder Links: ADC124S021



ADC124S021 Converter Electrical Characteristics (1)

The following specifications apply for $V_A = +2.7V$ to 5.25V, GND = 0V, $f_{SCLK} = 0.8$ MHz to 3.2 MHz, $f_{SAMPLE} = 50$ ksps to 200 ksps, $C_L = 35$ pF, unless otherwise noted. **Boldface limits apply for T_A = T_{MIN} to T_{MAX}**: all other limits $T_A = 25^{\circ}C$.

Symbol	Parameter	Conditions	Typical	Limits (2)	Units
STATIC C	CONVERTER CHARACTERISTICS		1		
	Resolution with No Missing Codes			12	Bits
NII	Internal New Linearity		+0.35	+0.8	LSB (max)
INL	Integral Non-Linearity		-0.35	-1.1	LSB (min)
DNII	Differential New Houselfer		+0.4	+1.1	LSB (max)
DNL	Differential Non-Linearity		-0.2	-0.8	LSB (min)
√ _{OFF}	Offset Error		+0.37	±1.3	LSB (max)
DEM	Channel to Channel Offset Error Match		±0.1	±1.0	LSB (max)
FSE	Full-Scale Error		±0.52	±1.5	LSB (max)
FSEM	Channel to Channel Full-Scale Error Match		±0.1	±1.0	LSB (max)
DYNAMIC	CONVERTER CHARACTERISTICS				
SINAD	Signal-to-Noise Plus Distortion Ratio	$V_A = +2.7 \text{ to } 5.25V$ $f_{IN} = 39.9 \text{ kHz}, -0.02 \text{ dBFS}$	72	69.2	dB (min)
SNR	Signal-to-Noise Ratio	$V_A = +2.7 \text{ to } 5.25V$ $f_{IN} = 39.9 \text{ kHz}, -0.02 \text{ dBFS}$	72	70.6	dB (min)
THD	Total Harmonic Distortion	$V_A = +2.7 \text{ to } 5.25V$ $f_{IN} = 39.9 \text{ kHz}, -0.02 \text{ dBFS}$	-84	-75	dB (max)
SFDR	Spurious-Free Dynamic Range	$V_A = +2.7 \text{ to } 5.25V$ $f_{IN} = 39.9 \text{ kHz}, -0.02 \text{ dBFS}$	86	76	dB (min)
ENOB	Effective Number of Bits	$V_A = +2.7 \text{ to } 5.25V$	11.7	11.2	Bits (min)
	Channel-to-Channel Crosstalk	$V_A = +5.25V$ $f_{IN} = 39.9 \text{ kHz}$	-86		dB
IMD	Intermodulation Distortion, Second Order Terms	$V_A = +5.25V$ $f_a = 40.161 \text{ kHz}, f_b = 41.015 \text{ kHz}$	-87		dB
	Intermodulation Distortion, Third Order Terms	$V_A = +5.25V$ $f_a = 40.161 \text{ kHz}, f_b = 41.015 \text{ kHz}$	-88		dB
FPBW	-3 dB Full Power Bandwidth	$V_A = +5V$	11		MHz
	o ab i an i onei banaman	$V_A = +3V$	8		MHz
ANALOG	INPUT CHARACTERISTICS				
√ _{IN}	Input Range		0 to V _A		V
DCL	DC Leakage Current		±0.02	±1	μA (max)
C _{INA}	Input Capacitance	Track Mode	33		pF
○INA	mpar Capacitanic	Hold Mode	3		pF
DIGITAL	INPUT CHARACTERISTICS				
√ _{IH}	Input High Voltage	$V_A = +5.25V$		2.4	V (min)
▼ IH	mpacingii voltago	$V_A = +3.6V$		2.1	V (min)
/ _{IL}	Input Low Voltage			0.8	V (max)
IN	Input Current	$V_{IN} = 0V \text{ or } V_A$	±0.02	±10	μA (max)
C _{IND}	Digital Input Capacitance		2	4	pF (max)
DIGITAL (OUTPUT CHARACTERISTICS				
.,	Output High Voltage	I _{SOURCE} = 200 μA	V _A - 0.03	V _A - 0.5	V (min)
V _{OH}	Output High Voltage	I _{SOURCE} = 1 mA	V _A - 0.1		V
.,	Outside Law Vallage	I _{SINK} = 200 μA	0.02	0.4	V (max)
V_{OL}	Output Low Voltage	I _{SINK} = 1 mA	0.1		V
l _{ozh} , l _{ozl}	TRI-STATE® Leakage Current		±0.01	±1	μA (max)

Product Folder Links: ADC124S021

Min/max specification limits are guaranteed by design, test, or statistical analysis.

Tested limits are guaranteed to National's AOQL (Average Outgoing Quality Level). (2)



ADC124S021 Converter Electrical Characteristics (1) (continued)

The following specifications apply for V_A = +2.7V to 5.25V, GND = 0V, f_{SCLK} = 0.8 MHz to 3.2 MHz, f_{SAMPLE} = 50 ksps to 200 ksps, C_L = 35 pF, unless otherwise noted. **Boldface limits apply for T_A = T_{MIN} to T_{MAX}**: all other limits T_A = 25°C.

Symbol	Parameter	Conditions	Typical	Limits	Units
C _{OUT}	TRI-STATE® Output Capacitance		2	4	pF (max)
	Output Coding		Str	aight (Natural) Binary
POWER S	SUPPLY CHARACTERISTICS (C _L = 10 p	F)			
\/	Supply Voltage			2.7	V (min)
V_A	Supply voltage			5.25	V (max)
	Supply Current, Normal Mode	$V_A = +5.25V$ $f_{SAMPLE} = 200 \text{ ksps}, f_{IN} = 39.9 \text{ kHz}$	1.5	2.1	mA (max)
ı.	(Operational, CS low)	$V_A = +3.6V$, $f_{SAMPLE} = 200 \text{ ksps}$, $f_{IN} = 39.9 \text{ kHz}$	0.62	1.0	mA (max)
I _A Sur	Supply Current, Shutdown (CS high)	$V_A = +5.25V$ $f_{SAMPLE} = 0$ ksps	60		nA
		$V_A = +3.6V$, $f_{SAMPLE} = 0$ ksps	38		nA
Power Cons	Power Consumption, Normal Mode	$V_A = +5.25V$	7.9	11.0	mW (max)
P_D	(Operational, CS low)	$V_A = +3.6V$,	2.2	3.6	mW (max)
гD	Power Consumption, Shutdown (CS	$V_A = +5.25V$	0.32		μW
	high)	$V_A = +3.6V$,	0.14		μW
AC ELEC	TRICAL CHARACTERISTICS				
4	Maximum Clock Fraguesey (3)	(3)		0.8	MHz (min)
f _{SCLK}	Maximum Clock Frequency			3.2	MHz (max)
	Sample Rate	(3)		50	ksps (min)
f _S	Sample Rate			200	ksps (max)
t _{CONV}	Conversion Time			13	SCLK cycles
DC	SCLK Duty Cycle	f _{SCLK} = 3.2 MHz	50	30	% (min)
DC	SCLK Duty Cycle		50	70	% (max)
t _{ACQ}	Track/Hold Acquisition Time	Full-Scale Step Input		3	SCLK cycles
	Throughput Time	Acquisition Time + Conversion Time		16	SCLK cycles

⁽³⁾ This is the frequency range over which the electrical performance is guaranteed. The device is functional over a wider range which is specified under Operating Ratings.

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ADC124S021 Timing Specifications

The following specifications apply for V_A = +2.7V to 5.25V, GND = 0V, f_{SCLK} = 0.8 MHz to 3.2 MHz, f_{SAMPLE} = 50 ksps to 200 ksps, C_L = 35 pF, **Boldface limits apply for T_A = T_{MIN} to T_{MAX}**: all other limits T_A = 25°C.

Symbol	Parameter	Conditions		Typical	Limits	Units
	Catura Tiras COLIVIII de to CO Fallina Educ	(2)	$V_A = +3.0V$	-3.5	40	(:-)
t _{CSU}	Setup Time SCLK High to CS Falling Edge	K High to CS Failing Edge	$V_A = +5.0V$	-0.5	10	ns (min)
	Hold time CCLV Law to CS Folling Edge	(2)	$V_A = +3.0V$	+4.5	10	no (min)
t _{CLH}	Hold time SCLK Low to CS Falling Edge		$V_A = +5.0V$	+1.5	10	ns (min)
	t _{EN} Delay from \overline{CS} Until DOUT active		$V_A = +3.0V$	+4	20	no (mov)
^τ EN			$V_A = +5.0V$	+2	30	ns (max)
	Deta Assass Time ofter CCLK Falling Edge		$V_A = +3.0V$	+14.5	30	ns (max)
t _{ACC}	Data Access Time after SCLK Falling Edge		$V_A = +5.0V$	+13		
t _{SU}	Data Setup Time Prior to SCLK Rising Edge			+3	10	ns (min)
t_{H}	Data Valid SCLK Hold Time			+3	10	ns (min)
t _{CH}	SCLK High Pulse Width			0.5 x t _{SCLK}	0.3 x t _{SCLK}	ns (min)
t _{CL}	SCLK Low Pulse Width			0.5 x t _{SCLK}	0.3 x t _{SCLK}	ns (min)
		Output Folling	$V_A = +3.0V$	1.8		
t _{DIS}	CS Rising Edge to DOUT High-Impedance	Output Falling	$V_A = +5.0V$	1.3	20	ns (max)
		Output Bisina	V _A = +3.0V	1.0	20	
		Output Rising	Output Rising $V_A = +5.0V$	1.0		

- (1) Tested limits are guaranteed to National's AOQL (Average Outgoing Quality Level).
 (2) Clock may be either high or low when
 CS is asserted as long as setup and hold times t_{CSU} and t_{CLH} are strictly observed.

Timing Diagrams

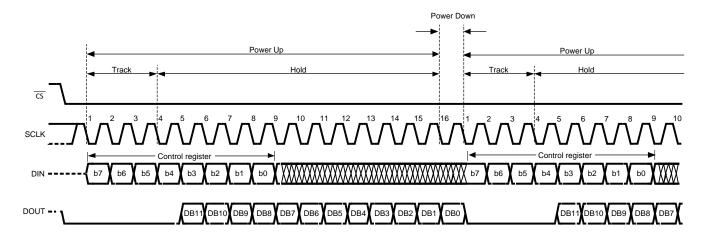


Figure 1. ADC124S021 Operational Timing Diagram



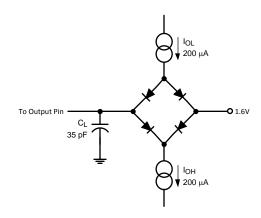


Figure 2. Timing Test Circuit

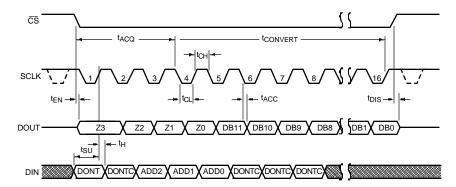


Figure 3. ADC124S021 Serial Timing Diagram

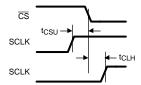


Figure 4. SCLK and CS Timing Parameters

Specification Definitions

ACQUISITION TIME is the time required to acquire the input voltage. That is, it is time required for the hold capacitor to charge up to the input voltage.

APERTURE DELAY is the time between the fourth falling SCLK edge of a conversion and the time when the input signal is acquired or held for conversion.

CONVERSION TIME is the time required, after the input voltage is acquired, for the ADC to convert the input voltage to a digital word.

CROSSTALK is the coupling of energy from one channel into the other channel, or the amount of signal energy from one analog input that appears at the measured analog input.

DIFFERENTIAL NON-LINEARITY (DNL) is the measure of the maximum deviation from the ideal step size of 1 LSB.

DUTY CYCLE is the ratio of the time that a repetitive digital waveform is high to the total time of one period. The specification here refers to the SCLK.

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EFFECTIVE NUMBER OF BITS (ENOB, or EFFECTIVE BITS) is another method of specifying Signal-to-Noise and Distortion or SINAD. ENOB is defined as (SINAD – 1.76) / 6.02 and says that the converter is equivalent to a perfect ADC of this (ENOB) number of bits.

FULL POWER BANDWIDTH is a measure of the frequency at which the reconstructed output fundamental drops 3 dB below its low frequency value for a full scale input.

FULL SCALE ERROR (FSE) is a measure of how far the last code transition is from the ideal $1\frac{1}{2}$ LSB below V_{RFF}^+ and is defined as:

$$V_{FSE} = V_{max} + 1.5 LSB - V_{REF}$$
 (1)

where V_{max} is the voltage at which the transition to the maximum code occurs. FSE can be expressed in Volts, LSB or percent of full scale range.

GAIN ERROR is the deviation of the last code transition (111...110) to (111...111) from the ideal $(V_{REF} - 1.5 LSB)$, after adjusting for offset error.

INTEGRAL NON-LINEARITY (INL) is a measure of the deviation of each individual code from a line drawn from negative full scale (½ LSB below the first code transition) through positive full scale (½ LSB above the last code transition). The deviation of any given code from this straight line is measured from the center of that code value.

INTERMODULATION DISTORTION (IMD) is the creation of additional spectral components as a result of two sinusoidal frequencies being applied to the ADC input at the same time. It is defined as the ratio of the power in the second and third order intermodulation products to the power in one of the original frequencies. IMD is usually expressed in dB.

MISSING CODES are those output codes that will never appear at the ADC outputs. These codes cannot be reached with any input value. The ADC124S021 is guaranteed not to have any missing codes.

OFFSET ERROR is the deviation of the first code transition (000...000) to (000...001) from the ideal (i.e. GND + 0.5 LSB).

SIGNAL TO NOISE RATIO (SNR) is the ratio, expressed in dB, of the rms value of the input signal to the rms value of the sum of all other spectral components below one-half the sampling frequency, not including d.c. or the harmonics included in THD.

SIGNAL TO NOISE PLUS DISTORTION (S/N+D or SINAD) Is the ratio, expressed in dB, of the rms value of the input signal to the rms value of all of the other spectral components below half the clock frequency, including harmonics but excluding d.c.

SPURIOUS FREE DYNAMIC RANGE (SFDR) is the difference, expressed in dB, between the desired signal amplitude to the amplitude of the peak spurious spectral component, where a spurious spectral component is any signal present in the output spectrum that is not present at the input and may or may not be a harmonic.

TOTAL HARMONIC DISTORTION (THD) is the ratio, expressed in dB or dBc, of the rms total of the first five harmonic components at the output to the rms level of the input signal frequency as seen at the output. THD is calculated as

THD =
$$20 \cdot \log_{10} \sqrt{\frac{A_{12}^2 + \dots + A_{16}^2}{A_{11}^2}}$$
 (2)

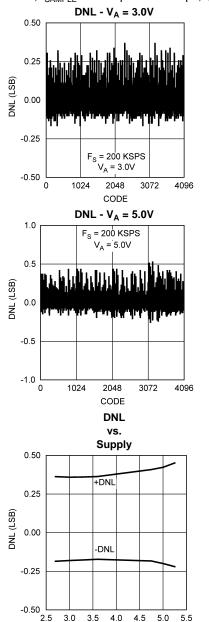
where Af_1 is the RMS power of the input frequency at the output and Af_2 through Af_6 are the RMS power in the first 5 harmonic frequencies.

THROUGHPUT TIME is the minimum time required between the start of two successive conversion. It is the acquisition time plus the conversion and read out times. In the case of the ADC124S021, this is 16 SCLK periods.

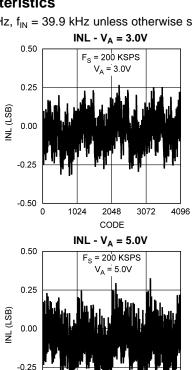


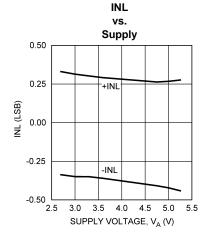
Typical Performance Characteristics

 T_A = +25°C, f_{SAMPLE} = 50 ksps to 200 ksps, f_{SCLK} = 0.8 MHz to 3.2 MHz, f_{IN} = 39.9 kHz unless otherwise stated.



SUPPLY VOLTAGE, $V_A(V)$





-0.50

0

1024

2048

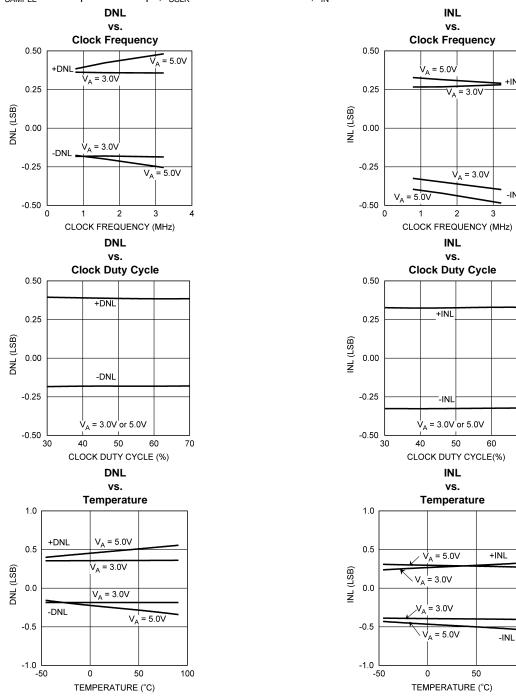
CODE

3072

4096



 T_A = +25°C, f_{SAMPLE} = 50 ksps to 200 ksps, f_{SCLK} = 0.8 MHz to 3.2 MHz, f_{IN} = 39.9 kHz unless otherwise stated.

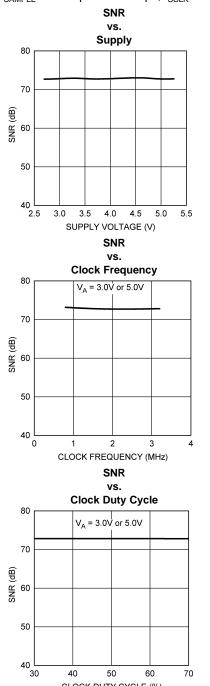


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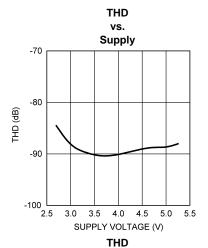
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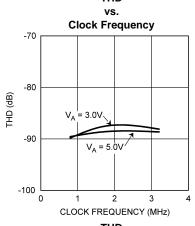


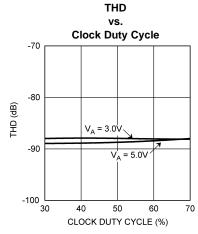
 T_A = +25°C, f_{SAMPLE} = 50 ksps to 200 ksps, f_{SCLK} = 0.8 MHz to 3.2 MHz, f_{IN} = 39.9 kHz unless otherwise stated.



CLOCK DUTY CYCLE (%)

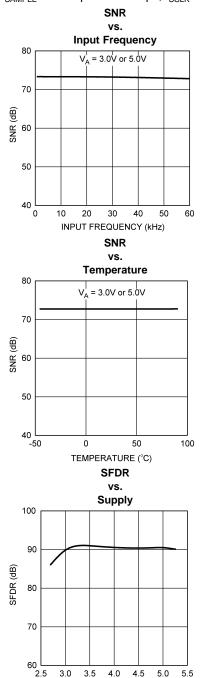




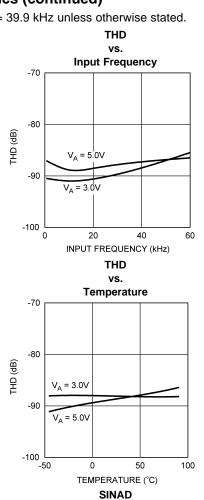


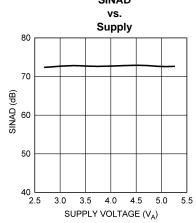


 T_A = +25°C, f_{SAMPLE} = 50 ksps to 200 ksps, f_{SCLK} = 0.8 MHz to 3.2 MHz, f_{IN} = 39.9 kHz unless otherwise stated.



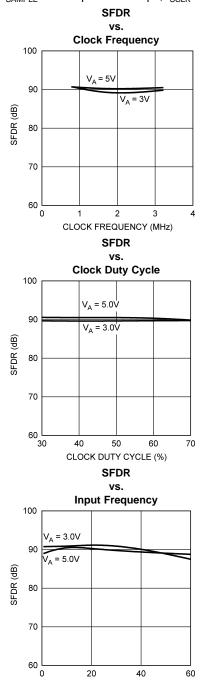
SUPPLY VOLTAGE (V_A)



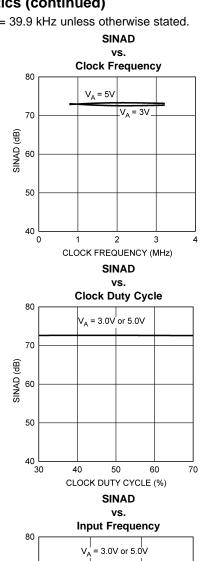


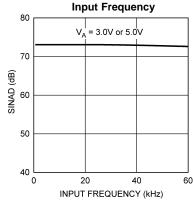


 T_A = +25°C, f_{SAMPLE} = 50 ksps to 200 ksps, f_{SCLK} = 0.8 MHz to 3.2 MHz, f_{IN} = 39.9 kHz unless otherwise stated.



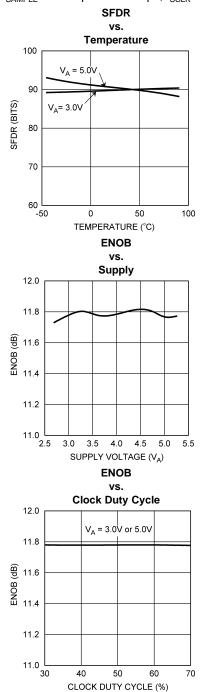
INPUT FREQUENCY (kHz)

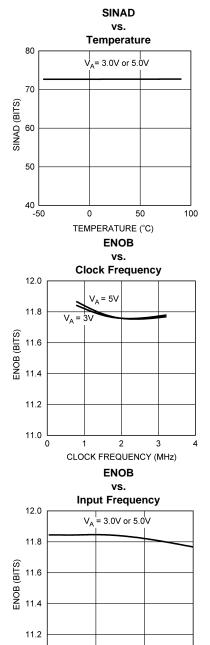






 T_A = +25°C, f_{SAMPLE} = 50 ksps to 200 ksps, f_{SCLK} = 0.8 MHz to 3.2 MHz, f_{IN} = 39.9 kHz unless otherwise stated.





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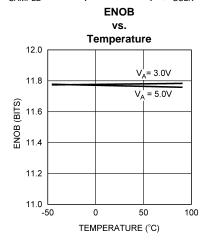
INPUT FREQUENCY (MHz)

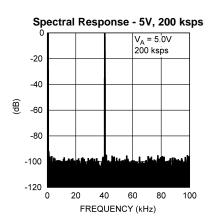
40

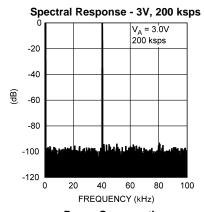
60

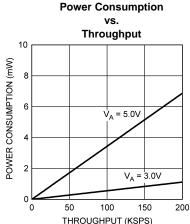


 $T_A = +25^{\circ}C$, $f_{SAMPLE} = 50$ ksps to 200 ksps, $f_{SCLK} = 0.8$ MHz to 3.2 MHz, $f_{IN} = 39.9$ kHz unless otherwise stated.









Applications Information

1.0 ADC124S021 OPERATION

The ADC124S021 is a successive-approximation analog-to-digital converter designed around a charge-redistribution digital-to-analog converter. Simplified schematics of the ADC124S021 in both track and hold modes are shown in Figure 5 Figure 6, respectively. In Figure 5, the ADC124S021 is in track mode: switch SW1 connects the sampling capacitor to one of four analog input channels through the multiplexer, and SW2 balances the comparator inputs. The ADC124S021 is in this state for the first three SCLK cycles after CS is brought low.

Figure 6 shows the ADC124S021 in hold mode: switch SW1 connects the sampling capacitor to ground, maintaining the sampled voltage, and switch SW2 unbalances the comparator. The control logic then instructs the charge-redistribution DAC to add fixed amounts of charge to the sampling capacitor until the comparator is balanced. When the comparator is balanced, the digital word supplied to the DAC is the digital representation of the analog input voltage. The ADC124S021 is in this state for the fourth through sixteenth SCLK cycles after $\overline{\text{CS}}$ is brought low.

The time when $\overline{\text{CS}}$ is low is considered a serial frame. Each of these frames should contain an integer multiple of 16 SCLK cycles, during which time a conversion is performed and clocked out at the DOUT pin and data is clocked into the DIN pin to indicate the multiplexer address for the next conversion.

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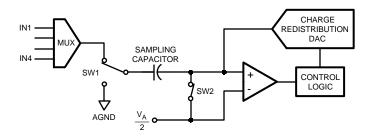


Figure 5. ADC124S021 in Track Mode

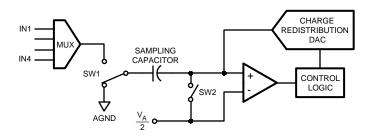


Figure 6. ADC124S021 in Hold Mode

2.0 USING THE ADC124S021

An ADC124S021 timing diagram and a serial interface timing diagram for the ADC124S021 are shown in the Timing Diagrams section. \overline{CS} is chip select, which initiates conversions and frames the serial data transfers. SCLK (serial clock) controls both the conversion process and the timing of serial data. DOUT is the serial data output pin, where a conversion result is sent as a serial data stream, MSB first. Data to be written to the ADC124S021's Control Register is placed on DIN, the serial data input pin. New data is written to the ADC at DIN with each conversion.

A serial frame is initiated on the falling edge of \overline{CS} and ends on the rising edge of \overline{CS} . Each frame must contain an integer multiple of 16 rising SCLK edges. The ADC output data (DOUT) is in a high impedance state when \overline{CS} is high and is active when \overline{CS} is low. Thus, \overline{CS} acts as an output enable. Additionally, the device goes into a power down state when \overline{CS} is high, and also between continuous conversion cycles.

During the first 3 cycles of SCLK, the ADC is in the track mode, acquiring the input voltage. For the next 13 SCLK cycles the conversion is accomplished and the data is clocked out, MSB first, starting on the 5th clock. If there is more than one conversion in a frame, the ADC will re-enter the track mode on the falling edge of SCLK after the N*16th rising edge of SCLK, and re-enter the hold/convert mode on the N*16+4th falling edge of SCLK, where "N" is an integer.

When $\overline{\text{CS}}$ is brought high, SCLK is internally gated off. If SCLK is stopped in the low state while $\overline{\text{CS}}$ is high, the subsequent fall of $\overline{\text{CS}}$ will generate a falling edge of the internal version of SCLK, putting the ADC into the track mode. This is seen by the ADC as the first falling edge of SCLK. If SCLK is stopped with SCLK high, the ADC enters the track mode on the first falling edge of SCLK after the falling edge of $\overline{\text{CS}}$.

During each conversion, data is clocked into the DIN pin on the first 8 rising edges of SCLK after the fall of \overline{CS} . For each conversion, it is necessary to clock in the data indicating the input that is selected for the conversion after the current one. See Tables 1, 2 and 3.

If $\overline{\text{CS}}$ and SCLK go low within the times defined by t_{CSU} and t_{CLH} , the rising edge of SCLK that begins clocking data in at DIN may be one clock cycle later than expected. It is, therefore, best to strictly observe the minimum t_{CSU} and t_{CLH} times given in the Timing Specifications.

There are no power-up delays or dummy conversions required with the ADC124S021. The ADC is able to sample and convert an input to full conversion immediately following power up. The first conversion result after power-up will be that of IN1.



Table 3. Control Register Bits

Bit 7 (MSI	B) Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
DONTC	DONTC	ADD2	ADD1	ADD0	DONTC	DONTC	DONTC

Table 4. Control Register Bit Descriptions

Bit #:	Symbol:	Description
7 - 6, 2 - 0	DONTC	Don't care. The value of these bits do not affect device operation.
5	ADD2	These three bits determine which input channel will be sampled and converted in the next
4	ADD1	track/hold cycle. The mapping between codes and channels is shown in Table 5.
3	ADD0	

Table 5. Input Channel Selection

ADD2	ADD1	ADD0	Input Channel
Х	0	0	IN1 (Default)
Х	0	1	IN2
Х	1	0	IN3
Х	1	1	IN4

3.0 ADC124S021 TRANSFER FUNCTION

The output format of the ADC124S021 is straight binary. Code transitions occur midway between successive integer LSB values. The LSB width for the ADC124S021 is $V_A/4096$. The ideal transfer characteristic is shown in Figure 3. The transition from an output code of 0000 0000 0000 to a code of 0000 0000 0001 is at 1/2 LSB, or a voltage of $V_A/8192$. Other code transitions occur at steps of one LSB.

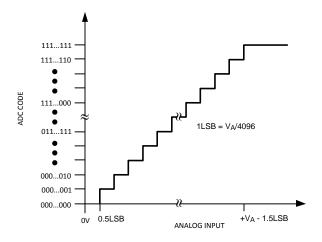


Figure 7. Ideal Transfer Characteristic

4.0 TYPICAL APPLICATION CIRCUIT

A typical application of the ADC124S021 is shown in Figure 8. Power is provided in this example by the National Semiconductor LP2950 low-dropout voltage regulator, available in a variety of fixed and adjustable output voltages. The power supply pin is bypassed with a capacitor network located close to the ADC124S021.

Because the reference for the ADC124S021 is the supply voltage, any noise on the supply will degrade device noise performance. To keep noise off the supply, use a dedicated linear regulator for this device, or provide sufficient decoupling from other circuitry to keep noise off the ADC124S021 supply pin. Because of the ADC124S021's low power requirements, it is also possible to use a precision reference as a power supply to maximize performance. The four-wire interface is also shown connected to a microprocessor or DSP.



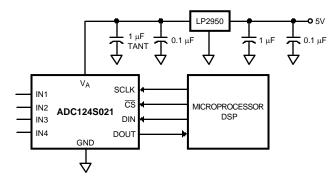


Figure 8. Typical Application Circuit

5.0 ANALOG INPUTS

An equivalent circuit for one of the ADC124S021's input channels is shown in Figure 5. Diodes D1 and D2 provide ESD protection for the analog inputs. At no time should any input go beyond (V_A + 300 mV) or (GND – 300 mV), as these ESD diodes will begin conducting, which could result in erratic operation. For this reason, these ESD diodes should NOT be used to clamp the input signal.

The capacitor C1 in Figure 5 has a typical value of 3 pF, and is mainly the package pin capacitance. Resistor R1 is the on resistance of the multiplexer and track / hold switch, and is typically 500 ohms. Capacitor C2 is the ADC124S021 sampling capacitor, and is typically 30 pF. The ADC124S021 will deliver best performance when driven by a low-impedance source to eliminate distortion caused by the charging of the sampling capacitance. This is especially important when using the ADC124S021 to sample AC signals. Also important when sampling dynamic signals is a band-pass or low-pass filter to reduce harmonics and noise, improving dynamic performance.

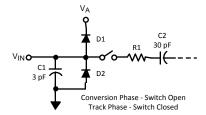


Figure 9. Equivalent Input Circuit

6.0 DIGITAL INPUTS AND OUTPUTS

The ADC124S021's digital output DOUT is limited by, and cannot exceed, the supply voltage, V_A . The digital input pins are not prone to latch-up and, and although not recommended, SCLK, \overline{CS} and DIN may be asserted before V_A without any latch-up risk.

7.0 POWER SUPPLY CONSIDERATIONS

The ADC124S021 is fully powered-up whenever $\overline{\text{CS}}$ is low, and fully powered-down whenever $\overline{\text{CS}}$ is high, with one exception: the ADC124S021 automatically enters power-down mode between the 16th falling edge of a conversion and the 1st falling edge of the subsequent conversion (see Timing Diagrams).

The ADC124S021 can perform multiple conversions back to back; each conversion requires 16 SCLK cycles. The ADC124S021 will perform conversions continuously as long as CS is held low.

The user may trade off throughput for power consumption by simply performing fewer conversions per unit time. The Power Consumption vs. Sample Rate curve in the Typical Performance Curves section shows the typical power consumption of the ADC124S021 versus throughput. To calculate the power consumption, simply multiply the fraction of time spent in the normal mode by the normal mode power consumption, and add the fraction of time spent in shutdown mode multiplied by the shutdown mode power dissipation.



7.1 Power Management

When the ADC124S021 is operated continuously in normal mode, the maximum throughput is f_{SCI k}/16. Throughput may be traded for power consumption by running f_{SCLK} at its maximum 3.2 MHz and performing fewer conversions per unit time, putting the ADC124S021 into shutdown mode between conversions. A plot of typical power consumption versus throughput is shown in the Typical Performance Curves section. To calculate the power consumption for a given throughput, multiply the fraction of time spent in the normal mode by the normal mode power consumption and add the fraction of time spent in shutdown mode multiplied by the shutdown mode power consumption. Generally, the user will put the part into normal mode and then put the part back into shutdown mode. Note that the curve of power consumption vs. throughput is nearly linear. This is because the power consumption in the shutdown mode is so small that it can be ignored for all practical purposes.

7.2 Power Supply Noise Considerations

The charging of any output load capacitance requires current from the power supply, V_A. The current pulses required from the supply to charge the output capacitance will cause voltage variations on the supply. If these variations are large enough, they could degrade SNR and SINAD performance of the ADC. Furthermore, discharging the output capacitance when the digital output goes from a logic high to a logic low will dump current into the die substrate, which is resistive. Load discharge currents will cause "ground bounce" noise in the substrate that will degrade noise performance if that current is large enough. The larger is the output capacitance, the more current flows through the die substrate and the greater is the noise coupled into the analog channel, degrading noise performance.

To keep noise out of the power supply, keep the output load capacitance as small as practical. If the load capacitance is greater than 35 pF, use a 100 Ω series resistor at the ADC output, located as close to the ADC output pin as practical. This will limit the charge and discharge current of the output capacitance and improve noise performance.

19-Nov-2012

PACKAGING INFORMATION

Orderable Device	Status	Package Type	_		Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Samples
	(1)		Drawing			(2)		(3)	(Requires Login)
ADC124S021CIMM	ACTIVE	VSSOP	DGS	10	1000	TBD	CU SNPB	Level-1-260C-UNLIM	
ADC124S021CIMM/NOPB	ACTIVE	VSSOP	DGS	10	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	
ADC124S021CIMMX	ACTIVE	VSSOP	DGS	10	3500	TBD	CU SNPB	Level-1-260C-UNLIM	
ADC124S021CIMMX/NOPB	ACTIVE	VSSOP	DGS	10	3500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

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Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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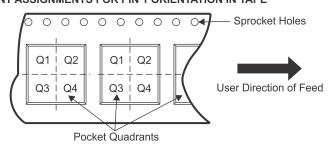
TAPE AND REEL INFORMATION





Γ	A0	Dimension designed to accommodate the component width
		Dimension designed to accommodate the component length
		Dimension designed to accommodate the component thickness
		Overall width of the carrier tape
	P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
ADC124S021CIMM	VSSOP	DGS	10	1000	178.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
ADC124S021CIMM/NOPB	VSSOP	DGS	10	1000	178.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
ADC124S021CIMMX	VSSOP	DGS	10	3500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
ADC124S021CIMMX/NOP B	VSSOP	DGS	10	3500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
ADC124S021CIMM	VSSOP	DGS	10	1000	203.0	190.0	41.0
ADC124S021CIMM/NOPB	VSSOP	DGS	10	1000	203.0	190.0	41.0
ADC124S021CIMMX	VSSOP	DGS	10	3500	349.0	337.0	45.0
ADC124S021CIMMX/NOP B	VSSOP	DGS	10	3500	349.0	337.0	45.0

DGS (S-PDSO-G10)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion.
- D. Falls within JEDEC MO-187 variation BA.



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